# Karmjit Singh Sandha

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/908661/publications.pdf

Version: 2024-02-01

| | | 1478280 | 1281743 |
|---|---|---|---|
| 19 | 135 | 6 | 11 |
| papers | citations | h-index | g-index |

| | | | |
|---|---|---|---|
| 19 | 19 | 19 | 60 |
| all docs | docs citations | times ranked | citing authors |

| # | Article | IF | Citations |
|---|---|---|---|
| 1 | Temperature-Dependent Modeling and Performance Evaluation of Multi-Walled CNT and Single-Walled CNT as Global Interconnects. Journal of Electronic Materials, 2015, 44, 4825-4835. | 1.0 | 27 |
| 2 | Coupled microalgalâ€“bacterial biofilm for enhanced wastewater treatment without energy investment. Journal of Water Process Engineering, 2021, 41, 102029. | 2.6 | 19 |
| 3 | Influence of temperature on MWCNT bundle, SWCNT bundle and copper interconnects for nanoscaled technology nodes. Journal of Materials Science: Materials in Electronics, 2015, 26, 6134-6142. | 1.1 | 17 |
| 4 | Performance and analysis of temperature dependent multi-walled carbon nanotubes as global interconnects at different technology nodes. Journal of Computational Electronics, 2015, 14, 469-476. | 1.3 | 15 |
| 5 | Comparative Analysis of Mixed CNTs and MWCNTs as VLSI Interconnects for Deep Sub-micron Technology Nodes. Journal of Electronic Materials, 2019, 48, 2543-2554. | 1.0 | 13 |
| 6 | Performance Analysis of Different Mixed-MWCNT Structures as VLSI Interconnects for Nano-Electronics IC Design. Journal of Nanoelectronics and Optoelectronics, 2018, 13, 357-367. | 0.1 | 8 |
| 7 | Mixed CNT bundles as VLSI interconnects for nanoscale technology nodes. Journal of Computational Electronics, 2021, 20, 248-258. | 1.3 | 7 |
| 8 | Thermally Aware Modeling and Performance Analysis of MLGNR as On-Chip VLSI Interconnect Material. Journal of Electronic Materials, 2019, 48, 4902-4912. | 1.0 | 6 |
| 9 | Impact of Intercalation Doping on the Conductivity of Multi-Layer Graphene Nanoribbon (MLGNR) in On-Chip Interconnects. Journal of Circuits, Systems and Computers, 2020, 29, 2050185. | 1.0 | 5 |
| 10 | Impact of tunneling conductance on the performance of multi walled carbon nanotubes as VLSI interconnects for nano-scaled technology nodes. Journal of Materials Science: Materials in Electronics, 2017, 28, 4818-4827. | 1.1 | 4 |
| 11 | Influence of variable temperature on performance of mixed-MWCNT, MWCNT and SWCNT nanostructures as interconnects for high-performance VLSI-IC design. Journal of Materials Science: Materials in Electronics, 2020, 31, 1828-1838. | 1.1 | 4 |
| 12 | Investigation on the combined effects of variable Fermi energies and temperatures on the performance of multilayer graphene nanoribbon as interconnects. Analog Integrated Circuits and Signal Processing, 2020, 104, 157-168. | 0.9 | 4 |
| 13 | Multilayer Graphene Nanoribbon (MLGNR) as VLSI Interconnect Material at Nano-scaled Technology Nodes. Transactions on Electrical and Electronic Materials, 2018, 19, 456-461. | 1.0 | 2 |
| 14 | Impact of thermally -aware environmental conditions on double gate carbon nanotube FET. Microelectronics Journal, 2021, 114, 105146. | 1.1 | 2 |
| 15 | Thermally-Aware Modeling and Performance Analysis of Mixed-MWCNTB as Very Large Scale Integrated Interconnects Material for Nano-Electronic Integrated Circuits Design. Journal of Nanoelectronics and Optoelectronics, 2019, 14, 1255-1266. | 0.1 | 1 |
| 16 | Stability- and Crosstalk-Based Performance of Multi- and Double-walled Mixed CNT Bundles as Interconnect for Next-Generation Technology Nodes. Journal of Circuits, Systems and Computers, 0, , . | 1.0 | 1 |
| 17 | Thermally aware modeling and performance for MWCNT bundle as VLSI interconnects for high performance integrated circuits. , 2015, , . | | 0 |
| 18 | Comparative Analysis of On-Chip Optical and Copper VLSI Interconnects for Deep Sub-Micron Technology Nodes. Journal of Nanoelectronics and Optoelectronics, 2018, 13, 267-274. | 0.1 | 0 |

| # | Article | IF | Citations |
|---|---|---|---|
| 19 | CNT as Interconnects. Advances in Computer and Electrical Engineering Book Series, 2020, , 130-159. | 0.2 | 0 |